

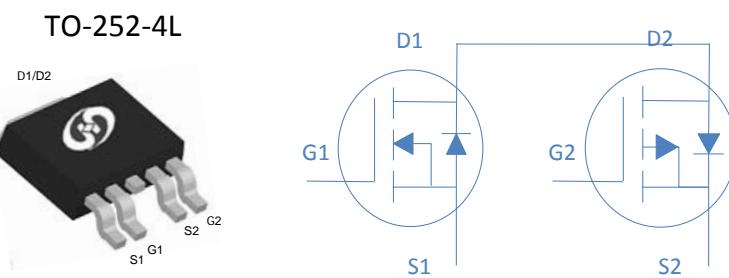
40V Complementary Power MOSFET
Feature

- ◇ High Speed Power Switching, Logic Level
- ◇ Enhanced Avalanche Ruggedness
- ◇ Lead Free, Halogen Free

	N-CH	P-CH	
V_{DS}	40	-40	V
$R_{DS(on),max}$	35	44	$m\Omega$
I_D (Silicon Limited)	12	-9	A

Application

- ◇ Hard Switching and High Speed Circuit
- ◇ BLDC motor



Part Number	Package	Marking
HTD350C04	TO-252	TD350C04

Absolute Maximum Ratings at $T_j=25^\circ C$ (unless otherwise specified)

Parameter	Symbol	Conditions	N-CH	P-CH	Unit
Continuous Drain Current (Silicon Limited)	I_D	$T_C=25^\circ C$	12	-9	A
		$T_C=100^\circ C$	8	-6	
Drain to Source Voltage	V_{DS}	-	40	-40	V
Gate to Source Voltage	V_{GS}	-	± 20		V
Pulsed Drain Current	I_{DM}	-	48	-36	A
Power Dissipation	P_D	$T_C=25^\circ C$	21		W
Operating and Storage Temperature	T_J, T_{stg}	-	-55 to 150		°C

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	42	°C/W
Thermal Resistance Junction-Case	$R_{\theta JC}$	6	°C/W

N-Channel Electrical Characteristics at $T_j=25^\circ\text{C}$ (unless otherwise specified)
Static Characteristics

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	40	-	-	V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=250\mu\text{A}$	1.8	2.3	3.2	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=32\text{V}, T_j=25^\circ\text{C}$	-	-	1	μA
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=30\text{V}, T_j=125^\circ\text{C}$	-	-	25	
Gate to Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	±100	nA
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=10\text{A}$	-	30	35	$\text{m}\Omega$
		$V_{\text{GS}}=7\text{V}, I_D=8\text{A}$	-	40	50	
Transconductance	g_{fs}	$V_{\text{DS}}=5\text{V}, I_D=10\text{A}$	-	19	-	S

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=20\text{V}, f=1\text{MHz}$	-	515	-	pF
Output Capacitance	C_{oss}		-	77	-	
Reverse Transfer Capacitance	C_{rss}		-	53	-	
Total Gate Charge	$Q_g(10\text{V})$	$V_{\text{DD}}=20\text{V}, I_D=15\text{A}, V_{\text{GS}}=10\text{V}$	-	13.1	-	nC
Gate to Source Charge	Q_{gs}		-	1.9	-	
Gate to Drain (Miller) Charge	Q_{gd}		-	4.1	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$		-	2.5	-	
Rise time	t_r	$V_{\text{DD}}=10\text{V}, I_D=1\text{A}, V_{\text{GS}}=10\text{V}, R_G=6\Omega$	-	7.5	-	ns
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	12	-	
Fall Time	t_f		-	4	-	

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_F=12\text{A}$	-		1.3	V
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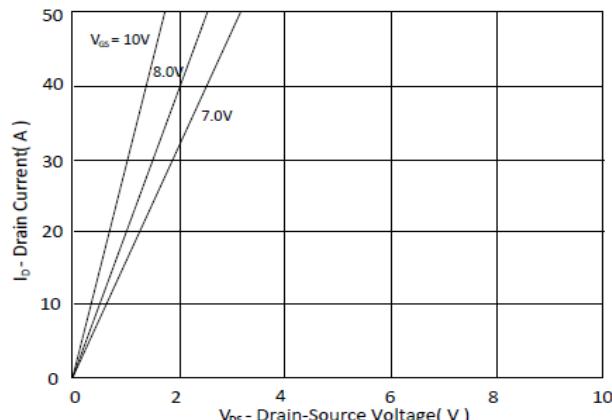
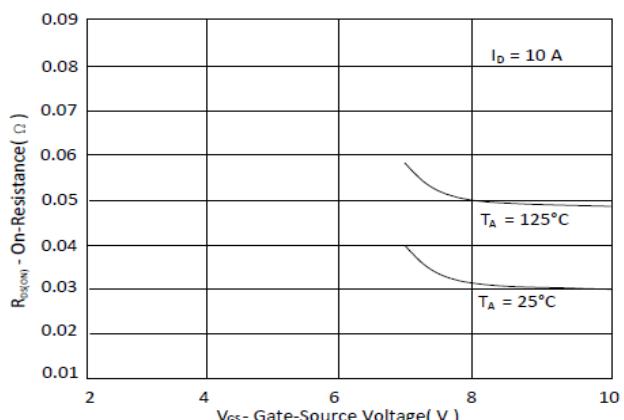
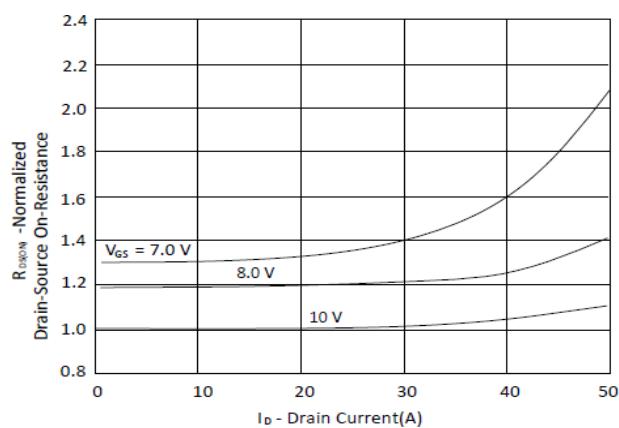
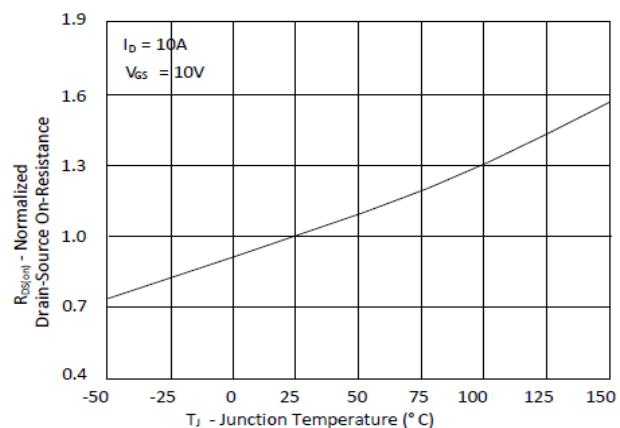
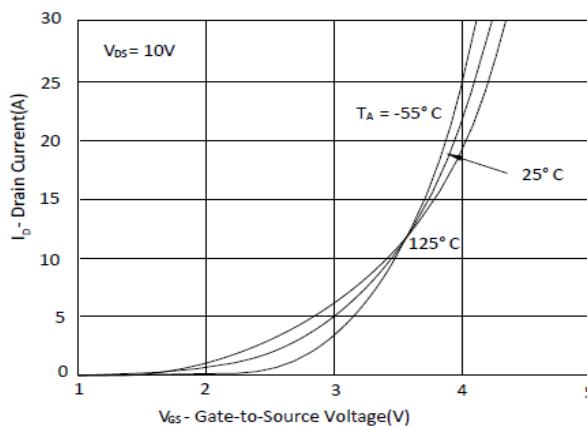
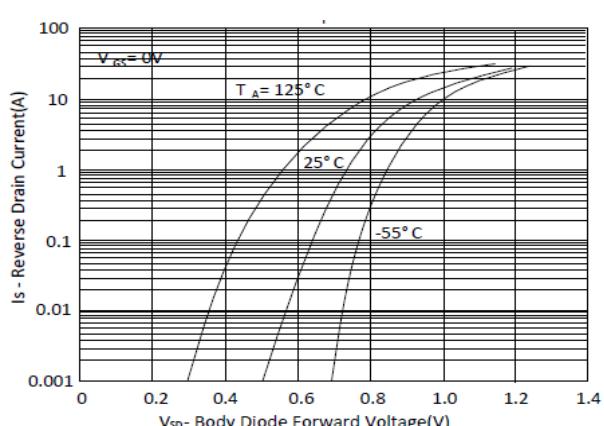
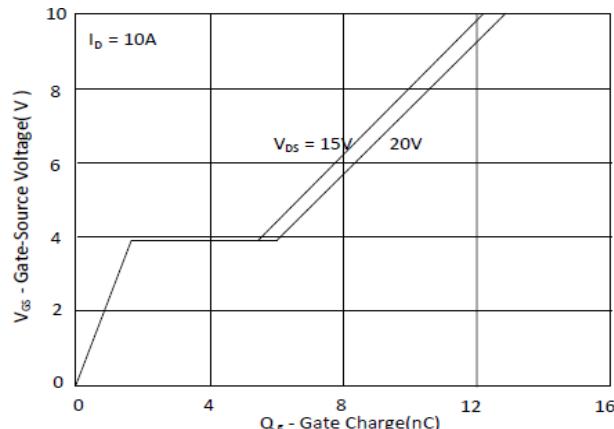
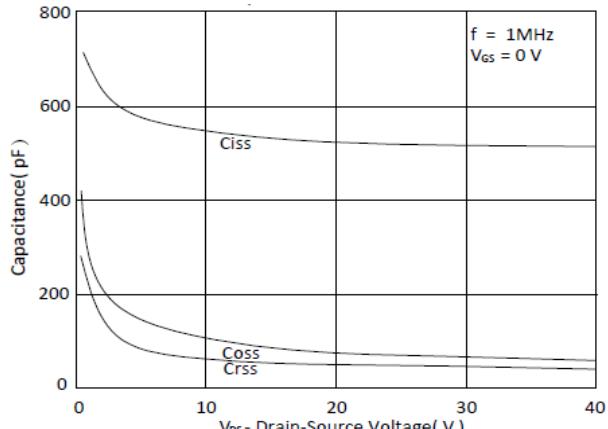
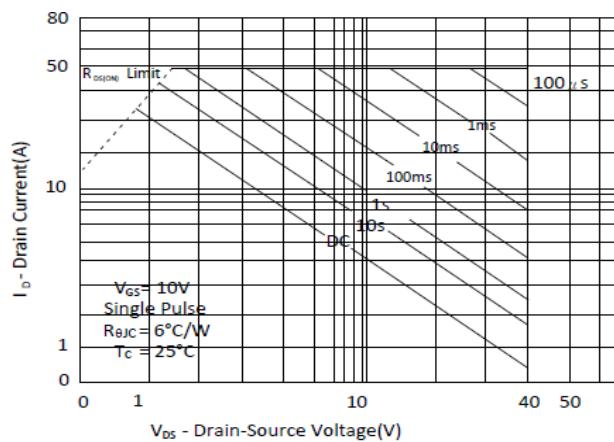
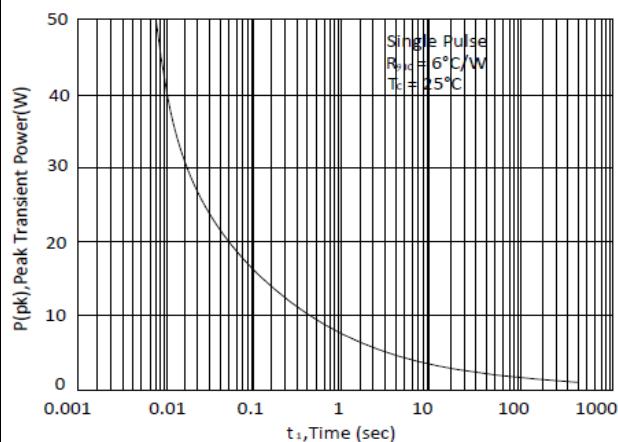
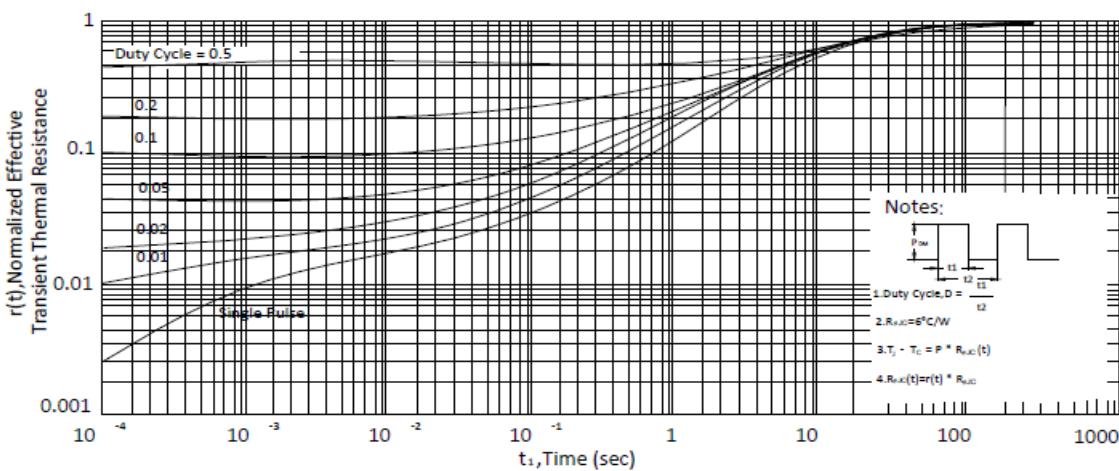
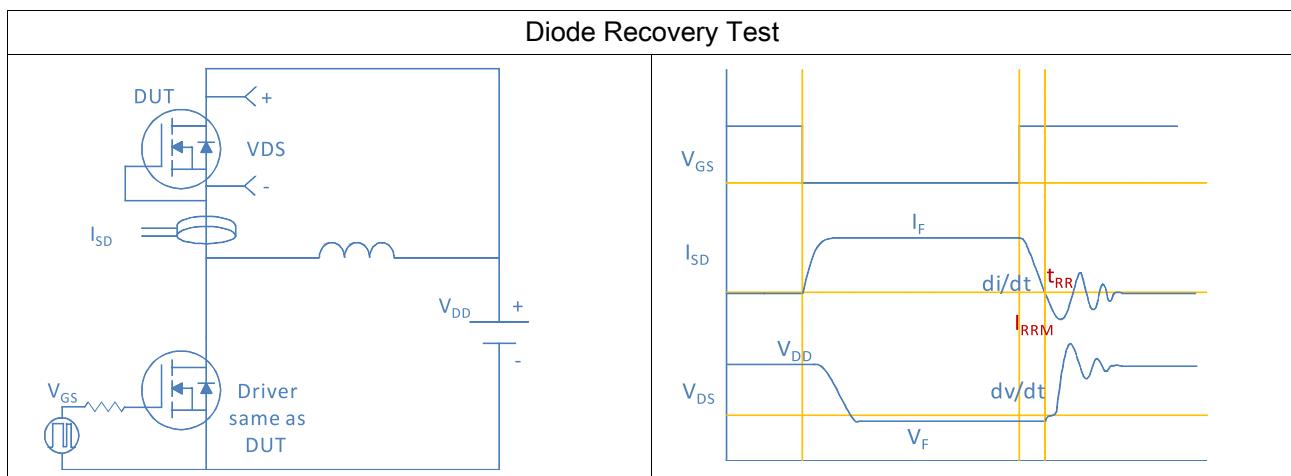
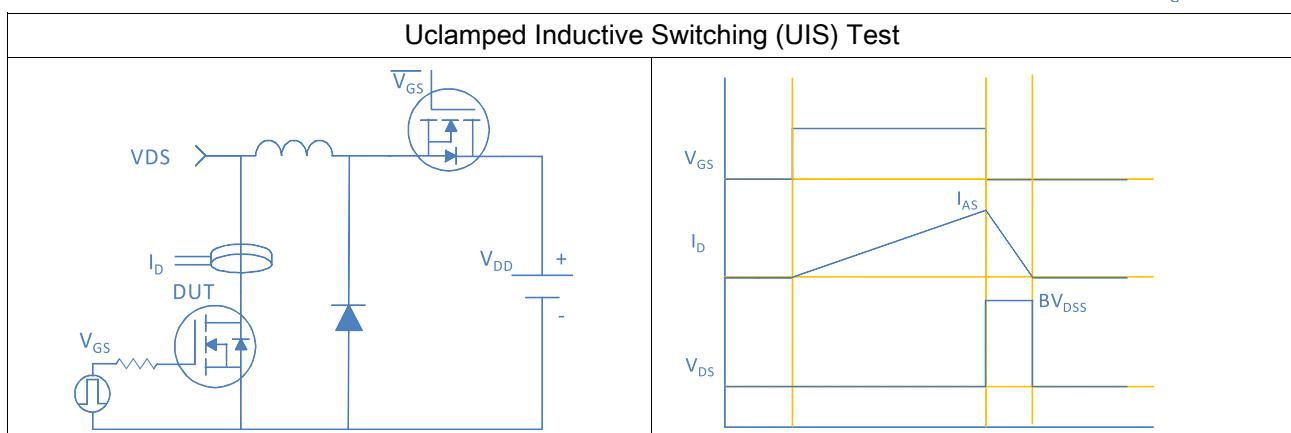
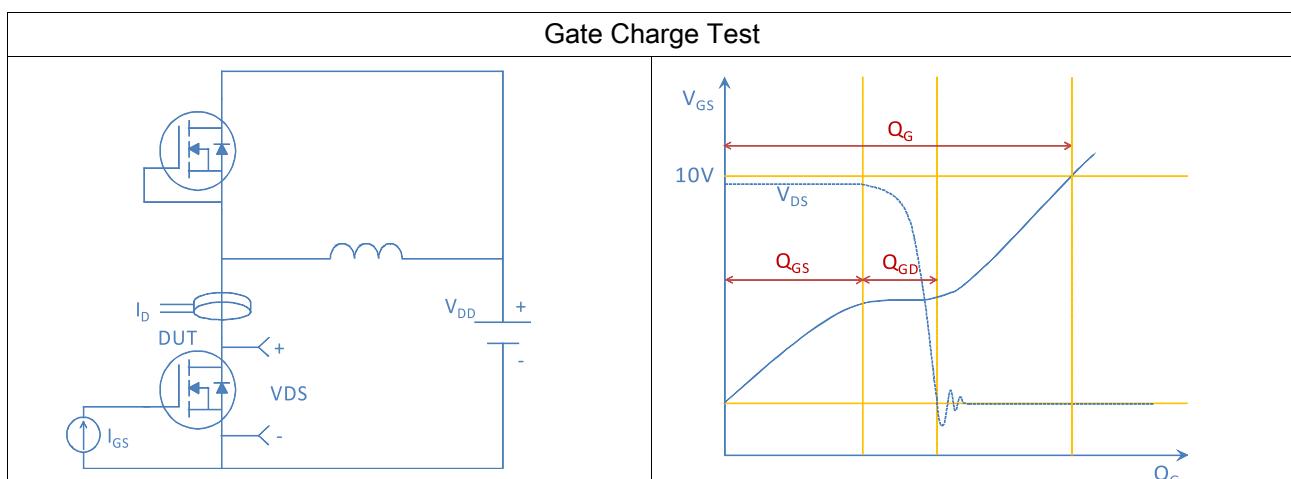
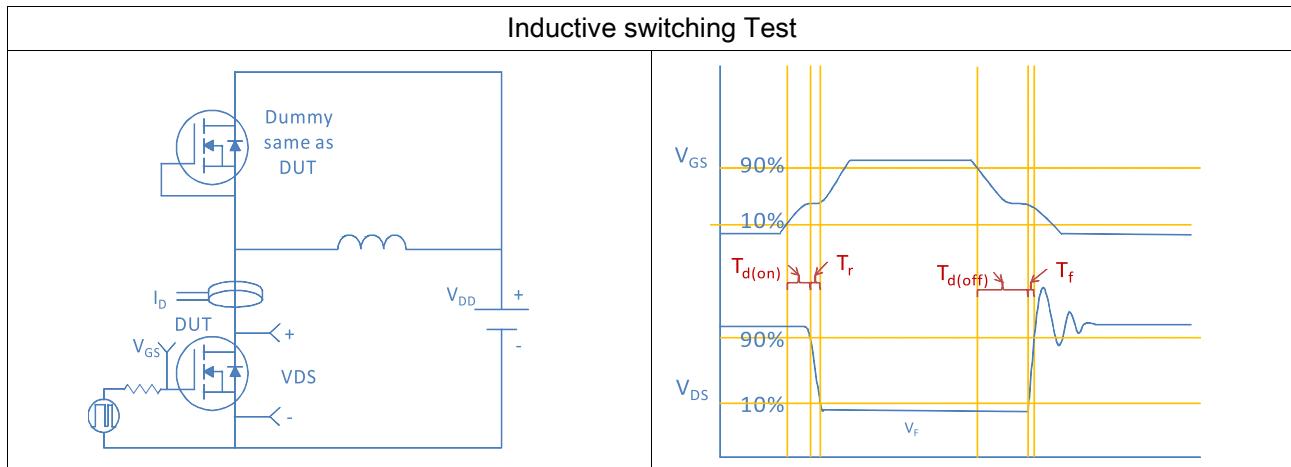
Fig 1. Typical Output Characteristics

Figure 2. On-Resistance vs. Gate-Source Voltage

Figure 3. On-Resistance vs. Drain Current and Gate Voltage

Figure 4. Normalized On-Resistance vs. Junction Temperature

Figure 5. Typical Transfer Characteristics

Figure 6. Typical Source-Drain Diode Forward Voltage


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient




P-Channel Electrical Characteristics at $T_j=25^\circ\text{C}$ (unless otherwise specified)
Static Characteristics

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	-40	-	-	V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=250\mu\text{A}$	-1.8	-2.3	-3.2	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-32\text{V}, T_j=25^\circ\text{C}$	-	-	-1	μA
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-30\text{V}, T_j=125^\circ\text{C}$	-	-	-25	
Gate to Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	±100	nA
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=-10\text{V}, I_D=-8\text{A}$	-	38	44	$\text{m}\Omega$
		$V_{\text{GS}}=-7\text{V}, I_D=-6\text{A}$	-	50	70	
Transconductance	g_{fs}	$V_{\text{DS}}=-5\text{V}, I_D=-8\text{A}$	-	11	-	S

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-20\text{V}, f=1\text{MHz}$	-	745	-	pF
Output Capacitance	C_{oss}		-	78	-	
Reverse Transfer Capacitance	C_{rss}		-	58	-	
Total Gate Charge	$Q_g (10\text{V})$	$V_{\text{DD}}=-20\text{V}, I_D=-10\text{A}, V_{\text{GS}}=-10\text{V}$	-	11.5	-	nC
Gate to Source Charge	Q_{gs}		-	2.5	-	
Gate to Drain (Miller) Charge	Q_{gd}		-	2.8	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=-10\text{V}, I_D=-1\text{A}, V_{\text{GS}}=-10\text{V}, R_G=6\Omega,$	-	7	-	ns
Rise time	t_r		-	10	-	
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	20	-	
Fall Time	t_f		-	12	-	

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_F=-12\text{A}$	-		-1.3	V
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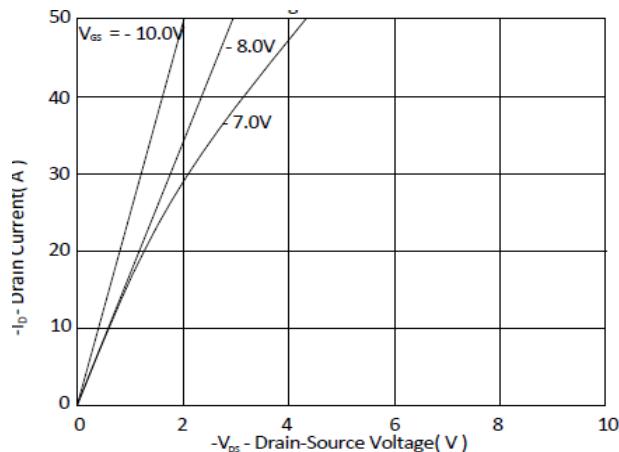
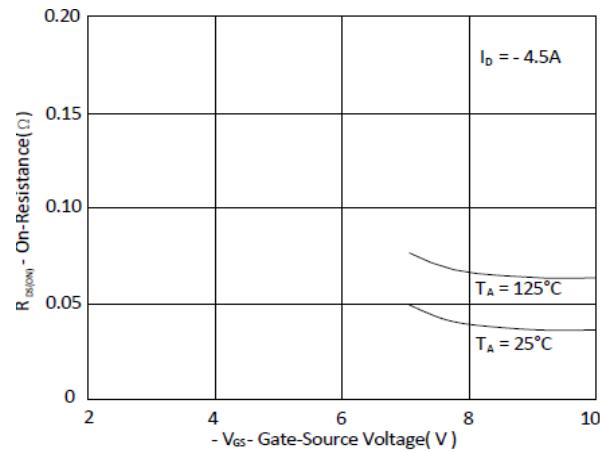
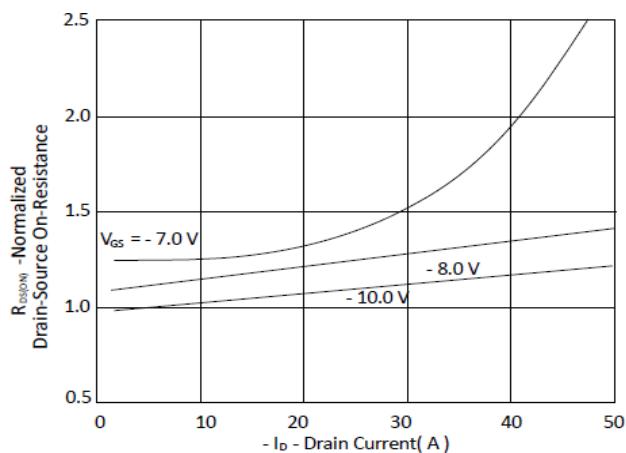
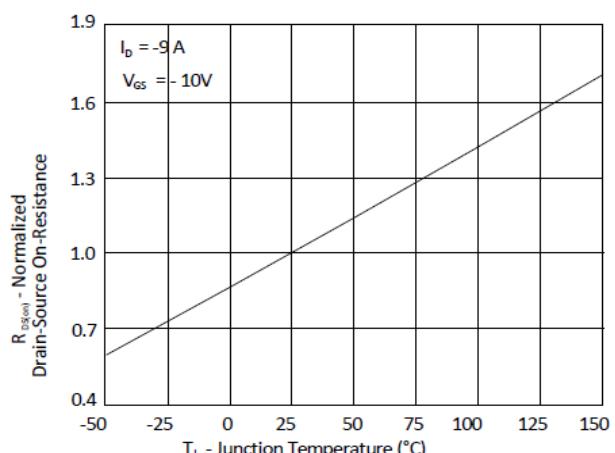
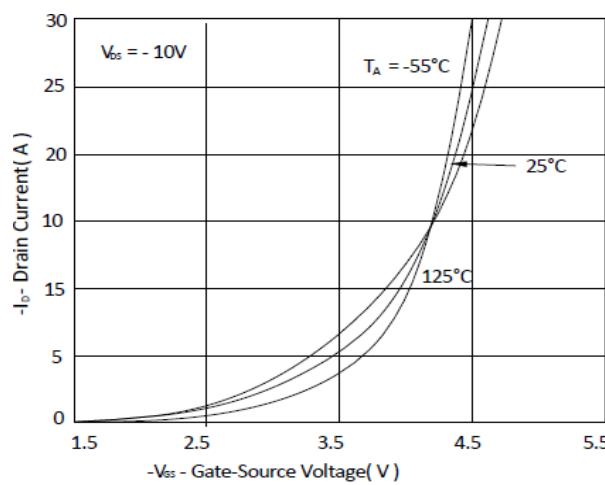
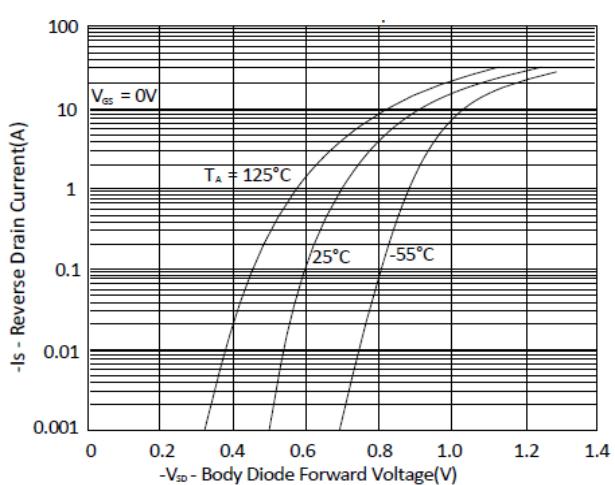
Fig 1. Typical Output Characteristics

Figure 2. On-Resistance vs. Gate-Source Voltage

Figure 3. On-Resistance vs. Drain Current and Gate Voltage

Figure 4. Normalized On-Resistance vs. Junction Temperature

Figure 5. Typical Transfer Characteristics

Figure 6. Typical Source-Drain Diode Forward Voltage


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

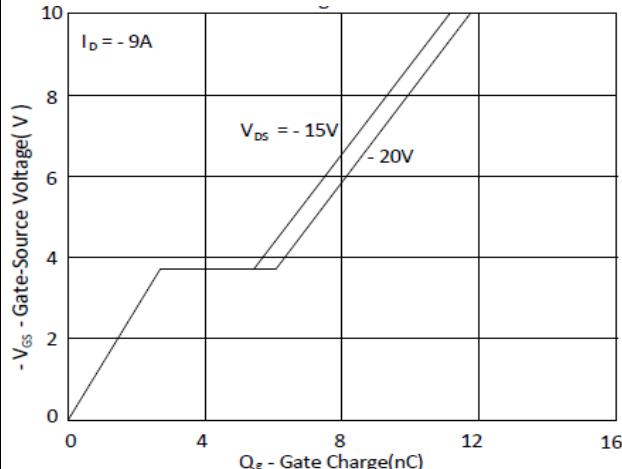


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

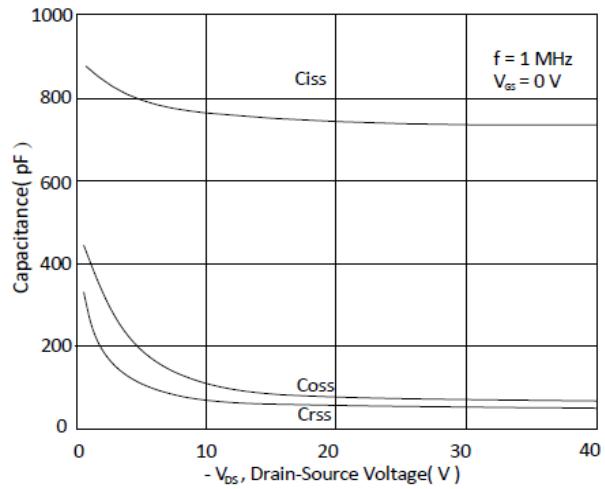


Figure 9. Maximum Safe Operating Area

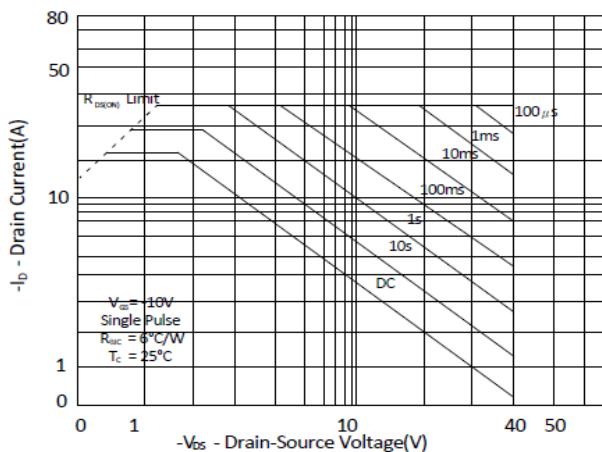


Figure 10. Maximum Drain Current vs. Case Temperature

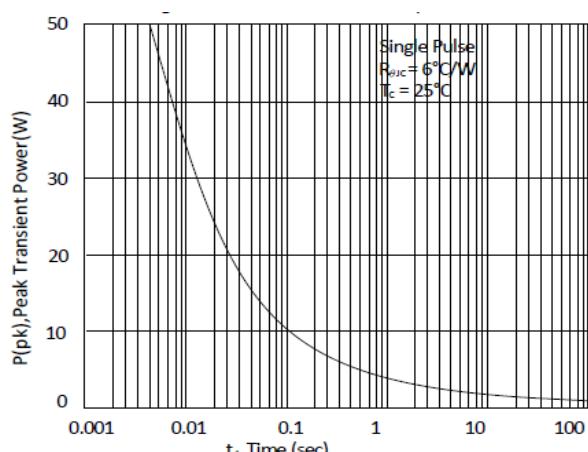
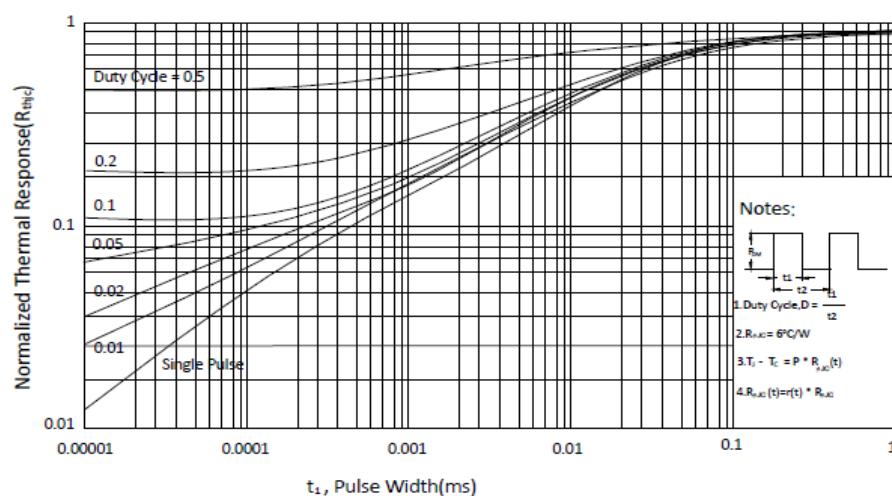
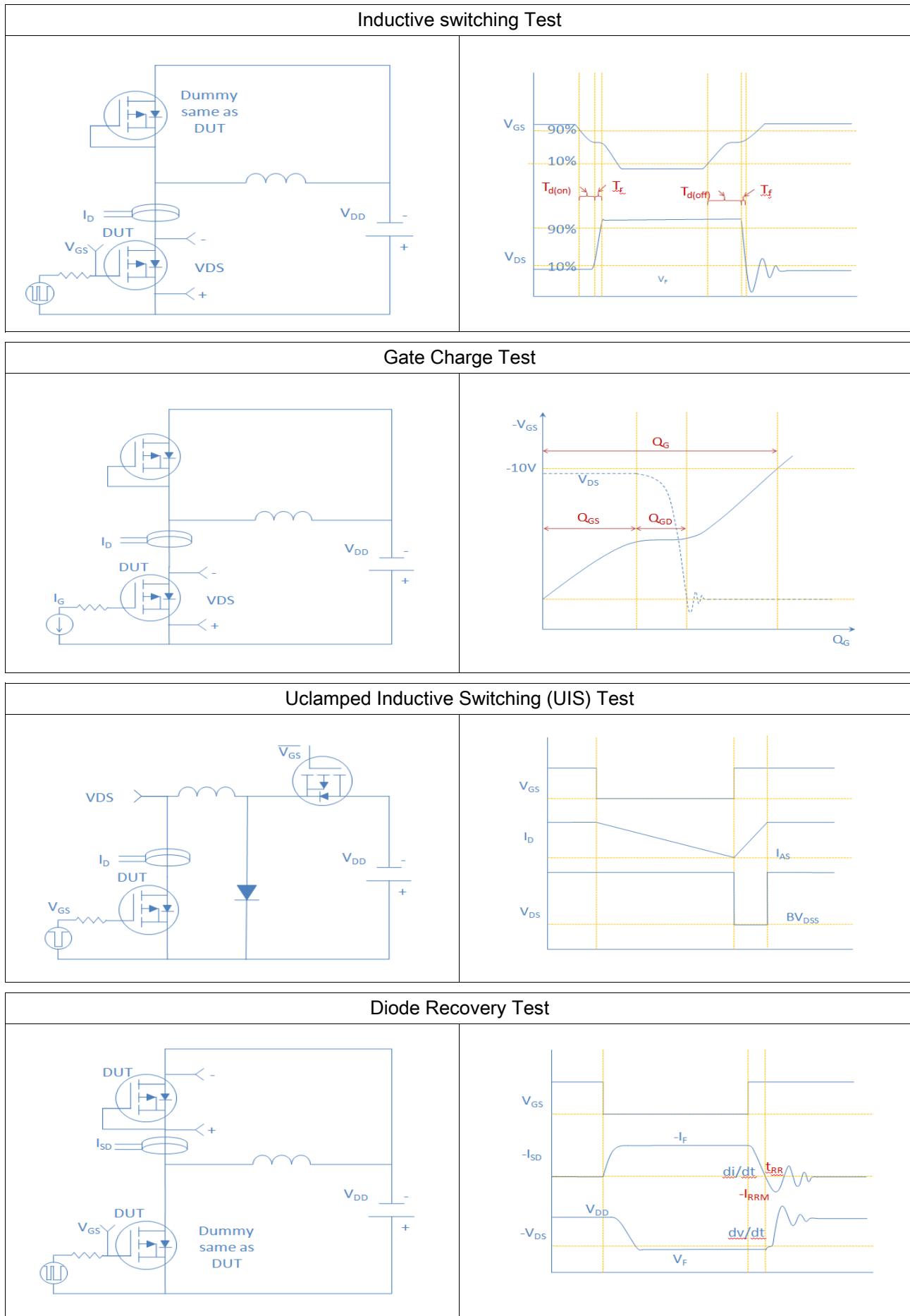


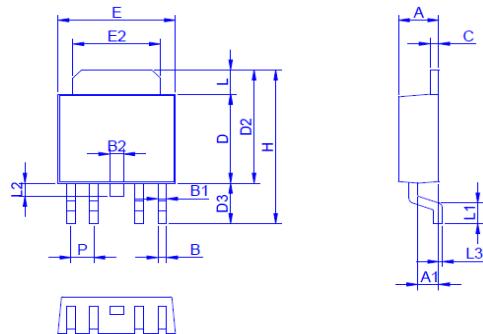
Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient





Package Outline

TO-252, 3leads



Dimension	A	A1	B	B1	B2	C	D	D2	D3	E	E2	H	L	L1	L2	L3	P
Min.	2.10	1.10	0.30	0.55	0.40	0.40	5.30	6.70	2.20	6.30	4.80	9.20	1.30	0.90	0.50	0.00	1.17
Max.	2.50	1.30	0.70	0.75	0.80	0.60	5.70	7.30	3.00	6.70	5.45	10.15	1.70	1.50	1.10	0.30	1.37